



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : Confirmation No. 9938  
Hiroshi TAKANASHI et al. : Docket No. 2001-0476  
Serial No. 09/838,118 : Group Art Unit 1752  
Filed April 20, 2001 : Examiner S. Lee

RECEIVED  
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TC 1700

NEGATIVE-WORKING PHOTOSENSITIVE :  
RESIN COMPOSITION AND  
PHOTOSENSITIVE RESIN PLATE USING :  
THE SAME

THE COMMISSIONER IS AUTHORIZED  
TO CHARGE ANY DEFICIENCY IN THE  
FEES FOR THIS PAPER TO DEPOSIT  
ACCOUNT NO. 23-0975

RESPONSE

Assistant Commissioner for Patents,  
Washington, D.C.

Sir:

In response to the Official Action dated November 21, 2001, please amend the present application as follows:

IN THE CLAIMS:

*Please amend claim 1 as follows:*

1. (Amended) A photosensitive resin plate comprising a support having formed thereon directly or via an adhesive layer a photosensitive layer of from 0.45 to 0.8 mm in thickness comprising a negative working photosensitive resin composition consisting essentially of (A) a film-forming polymer, (B) an unsaturated compound having a radical polymerizable ethylenic double bond, (C) a photopolymerization initiator, (D) a thermal polymerization inhibitor, and (E) at least one member selected from compounds represented by following formula (I):

$R^1-X$

(I)